

ALLWIN21 AccuThermo® AW610M RTP



TEXAS A&M UNIVERSITY

Department of Electrical
& Computer Engineering

Specifications:

- Wafer handling: Manual loading of wafer into the oven, single wafer processing
- Wafer sizes: 2", 3", 4", 5" and 6" wafers
- Ramp up rate: 15°C per second is preferred for all methods
- Recommended steady state duration: 0-300 seconds per step
- Ramp down rate: Programmable, 10°C to 125°C per second
- Recommended steady state temperature range: 150°C - 1150°C
- ERP temperature accuracy: $\pm 1^\circ\text{C}$, when calibrated against an instrumented thermocouple wafer (ITC)
- Thermocouple temperature accuracy: $\pm 0.5^\circ\text{C}$
- Temperature repeatability: $\pm 0.5^\circ\text{C}$ or better at 1150°C wafer-to-wafer. (Repetition specifications are based on a 100-wafer set.)
- Temperature uniformity: $\pm 5^\circ\text{C}$ across a 6" (150 mm) wafer at 1150°C
- Process/Purge gas inputs: Nitrogen (N_2) and forming gas (N_2H_2)

